MANUFACTURE METHOD FOR MANUFACTURING A WAFER STRUCTURE

Abstract

The application relates to a manufacture method (100) for manufacturing a wafer structure (232, 234). The manufacture method comprises a following step of establishing (102) a top wafer (204). The manufacture method further comprises a following step of depositing (112) a trap-rich layer (214) on the top wafer. The manufacture method further comprises a following step of bonding (122) a handle wafer (224) on the top wafer so that the trap-rich layer is between the top and handle wafers (204, 224) to produce the wafer structure. The wafer structure comprises the trap-rich layer bonded against the handle wafer so that a grain structure in the trap-rich layer is coarser adjacent to the handle wafer and a grain size in the grain structure decreases away from the handle wafer to improve a trapping efficiency of the wafer structure in the trap-rich layer in an interface (IF) towards the top wafer.

Fig. 1